

Title (en)

METHOD FOR PROCESSING ELECTRICAL COMPONENTS, ESPECIALLY SEMICONDUCTOR CHIPS, AND DEVICE FOR CARRYING OUT THE METHOD

Title (de)

VERFAHREN ZUM VERARBEITEN VON ELEKTRISCHEN BAUELEMENTEN, INSBESONDERE VON HALBLEITERCHIPS, SOWIE VORRICHTUNG ZUM DURCHFÜHREN DES VERFAHRENS

Title (fr)

PROCEDE DE TRAITEMENT DE COMPOSANTS ELECTRIQUES, NOTAMMENT DE PUCES A SEMI-CONDUCTEUR ET DISPOSITIF POUR METTRE LEDIT PROCEDE EN OEUVRE

Publication

**EP 1490894 A1 20041229 (DE)**

Application

**EP 03745743 A 20030402**

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- DE 10225097 A 20020605

Abstract (en)

[origin: WO03085702A1] The invention relates to a novel method for processing electrical components, especially semiconductor chips, which are respectively held in a detachable manner - as groups consisting of at least two components - by a first side thereof on a first carrier material of a first carrier.

IPC 1-7

**H01L 21/00**

IPC 8 full level

**H01L 21/60** (2006.01); **H01L 21/00** (2006.01)

CPC (source: EP US)

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C-Set (source: EP US)

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Citation (search report)

See references of WO 03085702A1

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DOCDB simple family (publication)

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